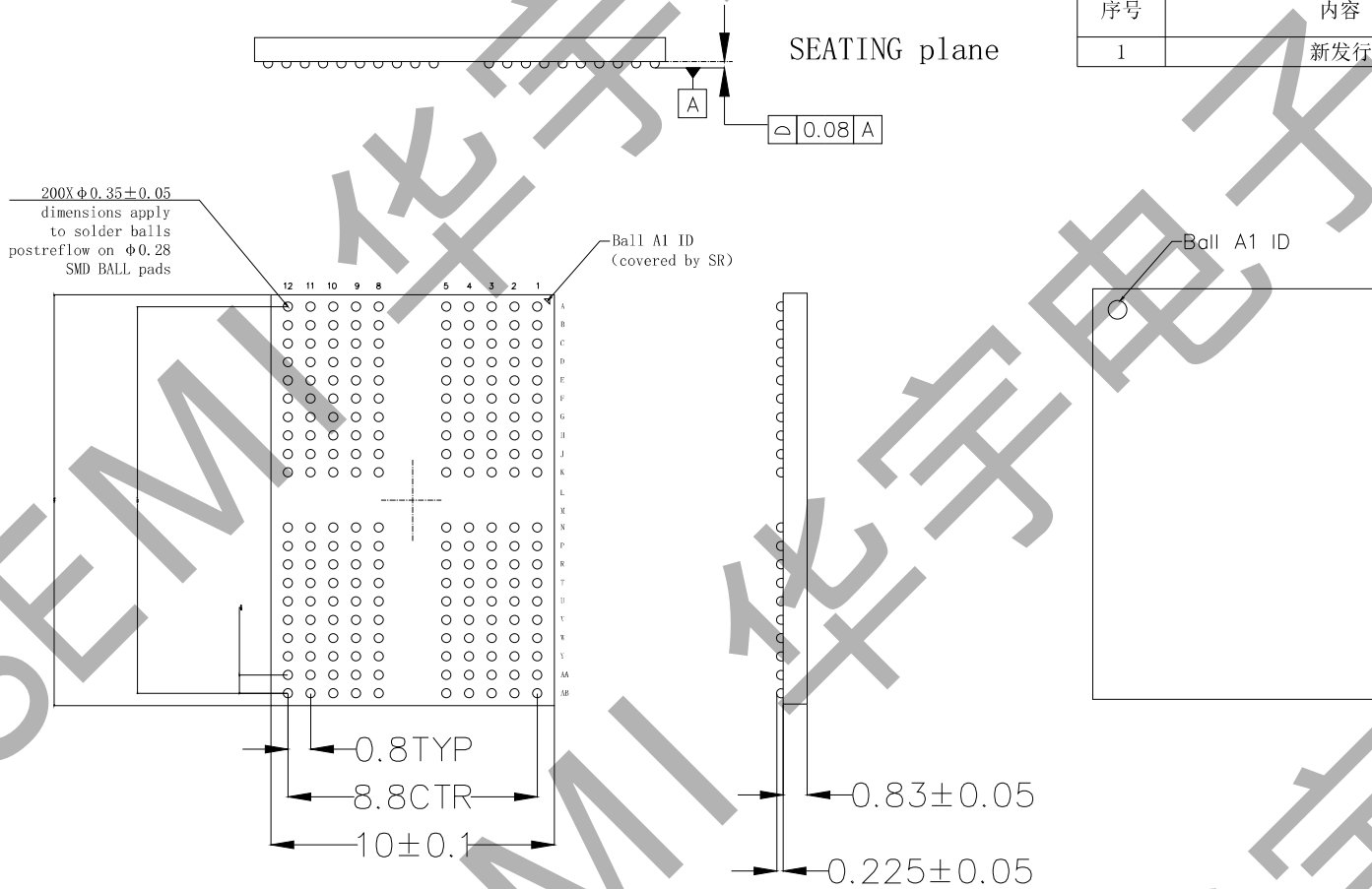


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RoSH



#### QUALITY SPECIFICATION

| ITEM                | SPEC. (mm) |
|---------------------|------------|
| Mold Thickness      | 0.6500     |
| Substrate Thickness | 0.1800     |
| Ball Size           | 0.3500     |

NOTES: 1.All dimensions are in millimeters.  
2.Solder ball composition:SAC302 with NiAu pads (Sn-3Ag-0.2Cu).

产品图

华宇电子

PROJECTION



TITLE:

SUBSTRATE DRAWING  
[基板图]  
FBGA-14.5X10  
240X77.5-1BLOCK

DRAWING NO.

SO-FBGA200B(145100)1298001

REV.

REV.

SIZE

PAGE

UNIT

DIMENSION AND TOLERANCES

SCALE

A3

1/4

MM

ASME Y14.5M

SCALE

SIGNATURE AREA

|                |  |
|----------------|--|
| DESIGN         |  |
| CHECK          |  |
| DESIGN APPROVE |  |
| PROCESS        |  |
| STAND.         |  |
| APPROVE        |  |

确认签字回传

履历

| 序号 | 内容  | 日期          |
|----|-----|-------------|
| 1  | 新发行 | 2025. 11. 4 |

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